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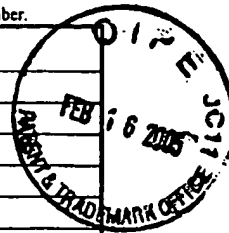
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Approved for use through 10/31/2002. OMB 0651-0031

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Substitute for form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Application Number	10/053,572
				Filing Date	January 24, 2002
				First Named Inventor	Hideto OHNUMA
				Group Art Unit	2812
				Examiner Name	J. Kennedy
Sheet	1	of	2	Attorney Docket Number	0756-2422



U.S. PATENT DOCUMENTS						
Examiner Initials [*]	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code ² (if known)			
JU		2001/0034089		Yamazaki et al.	10/25/2001	
JU		3,891,468		Ito et al.	06/24/1975	
JU		4,168,990		Lenie et al.	09/25/1979	
JU		4,169,740		Kalbitzer et al.	10/02/1979	
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JU		5,111,266		Furumura et al.	05/05/1992	
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Examiner Initials [*]	Cite No. ¹	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Office ³	Number ⁴	Kind Code ⁵ (if known)				
JU		JP	03-189626			08/19/1991		Abst.
JU		JP	04-290467			10/15/1992		Abst.
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JU		JP	10-302707			11/13/1998		Abst.
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OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		T ²
JU		Y. MISHIMA et al., <i>Implantation Temperature Effect on Polycrystalline Silicon By Ion Shower Doping</i> , Journal of Applied Physics, Vol. 74, No. 12, December 15, 1993, Pages 7114-7117.		/
JU		S. WOLF, et al., <i>Silicon Processing for the VLSI Era</i> , Vol. 1, January 1, 1986, Pages 175-180, 323-325.		
JU		H. SCHENK, et al., <i>Polymers for Light Emitting Diodes</i> , Proceedings of the 19 th International Display Research Conference, September 6, 1999, Pages 33-37.		

Examiner Signature	<i>James M. Kennedy</i>	Date Considered	Feb 25, 2005
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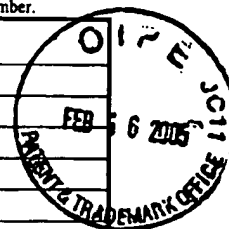
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Sheet	2	of	2



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		Number	Kind Code ² (if known)			
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Examiner Signature	<i>James M. Kennedy</i>	Date Considered	<i>Feb 25, 2005</i>
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